

Docket No.: 300.1152

Serial No. 10/821,915

**REMARKS**

In accordance with the foregoing, the specification has been corrected to render the specification consistent with the drawings which, together with the specification, make clear that the heat radiation layer 32 is formed on the back protective film 31 and seen for example on Fig. 6L.

Further, the claims have been amended to improve form, and as to claim 1, to incorporate the limitation of claim 2/1 which has been cancelled. The amendments to improve form moreover are responsive to the Examiner's helpful suggestions in Item 3 of the Action and further a new title responsive to Item 2 of the Action is also supplied.

In the Office Action, the Examiner has rejected claims 1 to 8 under 35 USC 102(a) as being anticipated by Tsai et al (USP6,713,856), claims 1, 7 and 9 under 35 USC 102(b) as being anticipated by Lauterbach et al. (USP6,313,517), and claims 10 under 35 USC 103(a) as being anticipated by USP'517.

Fig. 6 of USP'517 teaches a semiconductor device having a structure similar to that recited in claim 1 of this application, and Fig. 2 of USP'856 illustrates a thermally and electrically conductive planar member 27 which corresponds to a heat radiation layer 32 recited in claim 2 of this application. However, neither reference teaches a back surface protective film on the semiconductor package. The back surface protective layer 31 is illustrated, for example, in Fig. 4 and Figs. 6K to 6M and a heat radiation layer 32 is formed on the protection film 31.

No other references are cited as disclosing a back surface protective layer, as now recited in amended claim 1, and accordingly the same distinguishes patentably over the references and rejections of record.

**CONCLUSION**

There being no further outstanding objections or rejections, it is submitted that the application is in condition for allowance. An early action to that effect is courteously solicited.

Finally, if there are any formal matters remaining after this response, the Examiner is requested to telephone the undersigned to attend to these matters.

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If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

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**CERTIFICATE OF FACSIMILE TRANSMISSION**

I hereby certify that this correspondence is being transmitted via facsimile to: Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450

on April 17, 2006

STAAS & HALSEY

By: 

Date 4/17/06